

# BAV70WT1G, SBAV70WT1G

## Dual Switching Diode Common Cathode

### Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Reverse Voltage	V <sub>R</sub>	70	V
Forward Current	I <sub>F</sub>	200	mA
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### THERMAL CHARACTERISTICS

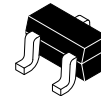
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200	mW
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	625	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300	mW
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

1. FR-5 = 1.0 × 0.75 × 0.062 in.
2. Alumina = 0.4 × 0.3 × 0.024 in. 99.5% alumina.

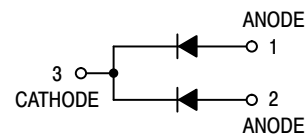


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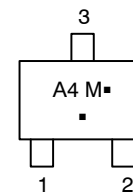
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SOT-323  
CASE 419  
STYLE 5



### MARKING DIAGRAM



A4 = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
BAV70WT1G	SOT-323 (Pb-Free)	3,000 / Tape & Reel
SBAV70WT1G	SOT-323 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# BAV70WT1G, SBAV70WT1G

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Breakdown Voltage ( $I_{BR} = 100 \mu\text{A}$ )	$V_{(BR)}$	70	–	V
Reverse Voltage Leakage Current (Note 3) ( $V_R = 70 \text{ V}$ ) ( $V_R = 50 \text{ V}$ )	$I_R$	– –	5.0 100	$\mu\text{A}$ nA
Forward Voltage ( $I_F = 1.0 \text{ mA}$ ) ( $I_F = 10 \text{ mA}$ ) ( $I_F = 50 \text{ mA}$ ) ( $I_F = 150 \text{ mA}$ )	$V_F$	– – – –	715 855 1000 1250	mV
Diode Capacitance ( $V_R = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$ )	$C_D$	–	1.5	pF
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}$ , $R_L = 100 \Omega$ , $I_{R(REC)} = 1.0 \text{ mA}$ ) (Figure 1)	$t_{rr}$	–	6.0	ns
Forward Recovery Voltage ( $I_F = 10 \text{ mA}$ , $t_r = 20 \text{ ns}$ ) (Figure 2)	$V_{RF}$	–	1.75	V

3. For each individual diode while the second diode is unbiased.

# BAV70WT1G, SBAV70WT1G

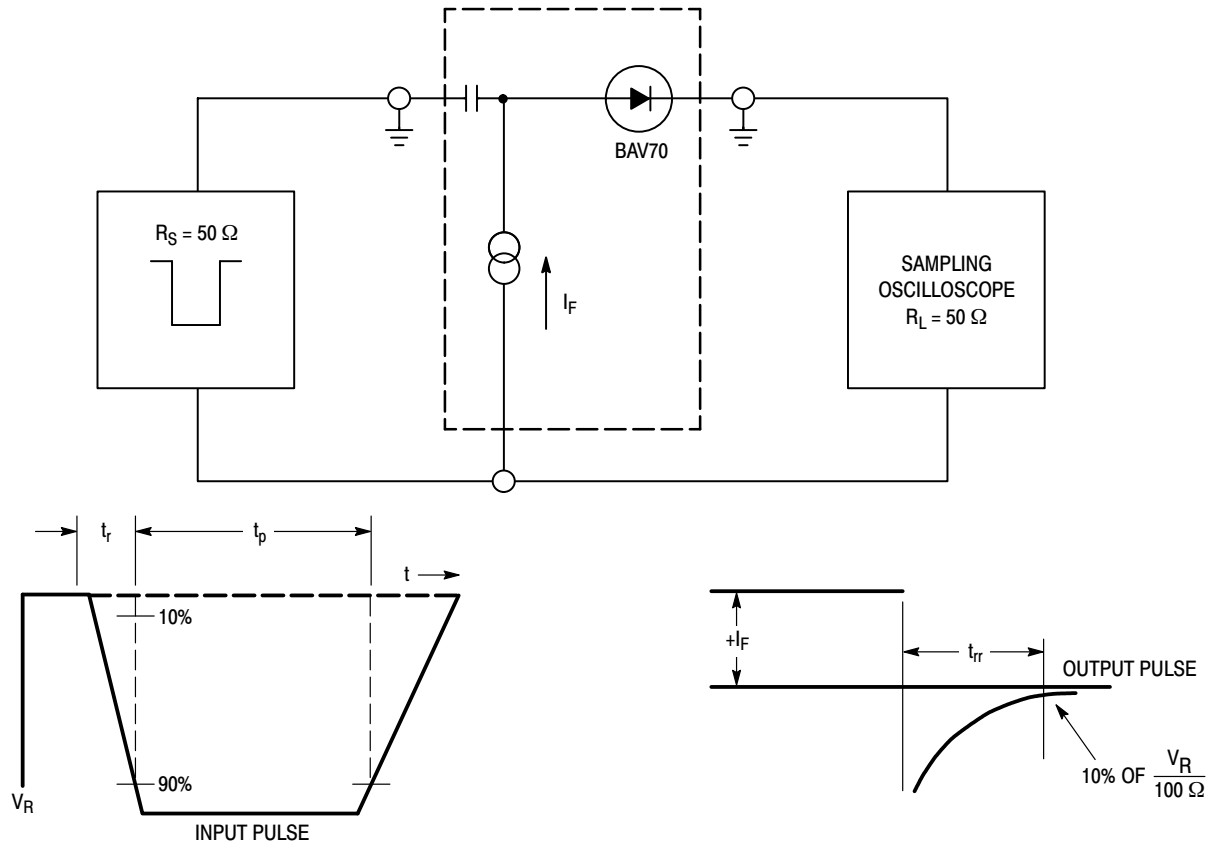


Figure 1. Recovery Time Equivalent Test Circuit

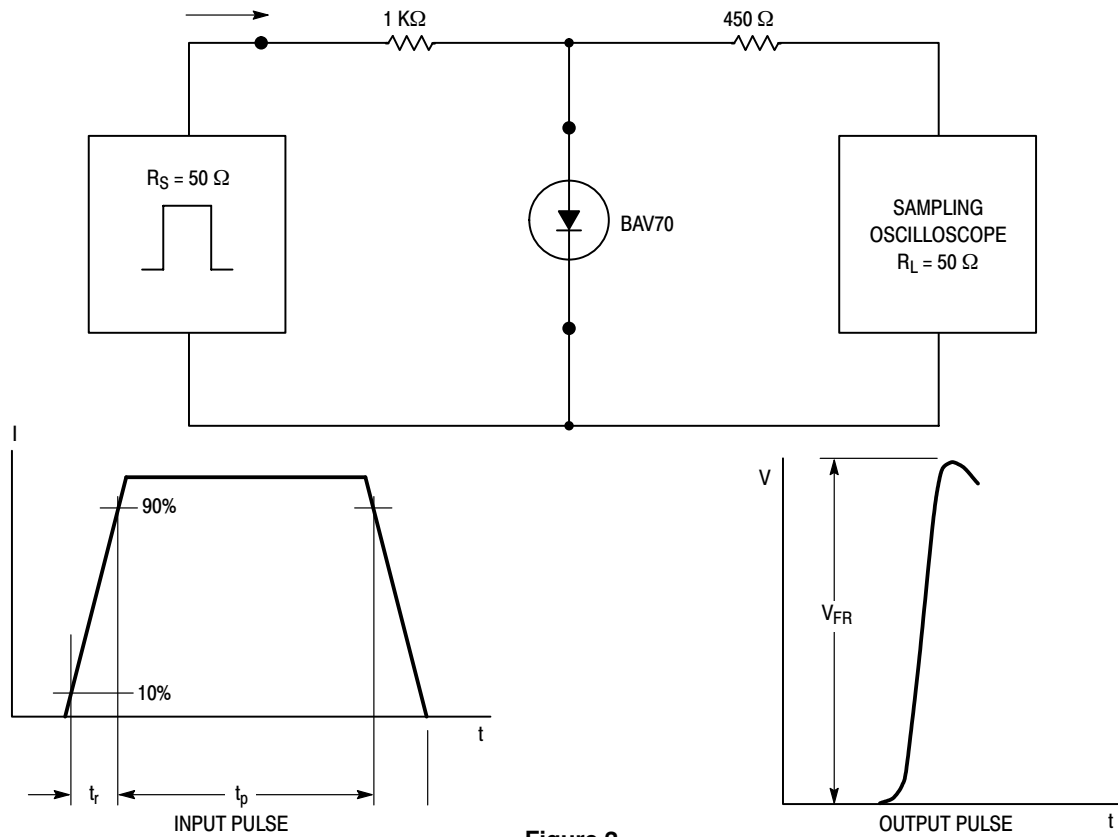


Figure 2.

# BAV70WT1G, SBAV70WT1G

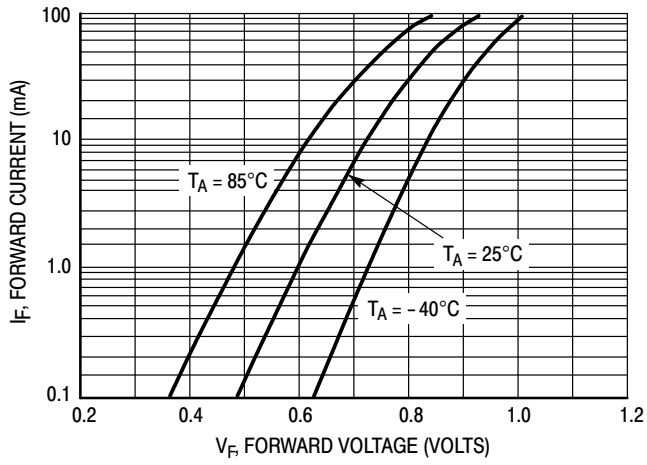


Figure 3. Forward Voltage

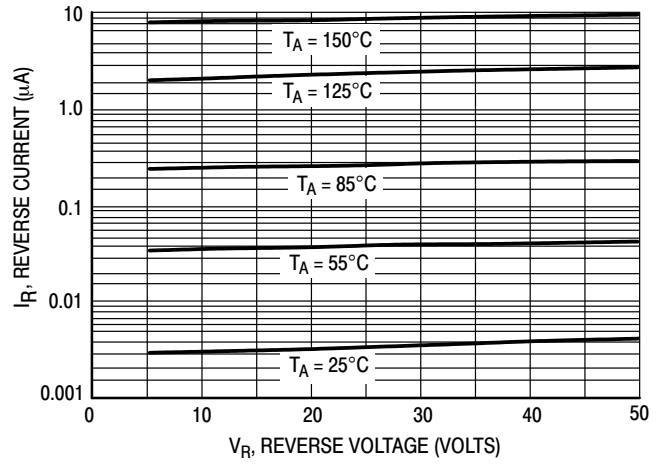


Figure 4. Leakage Current

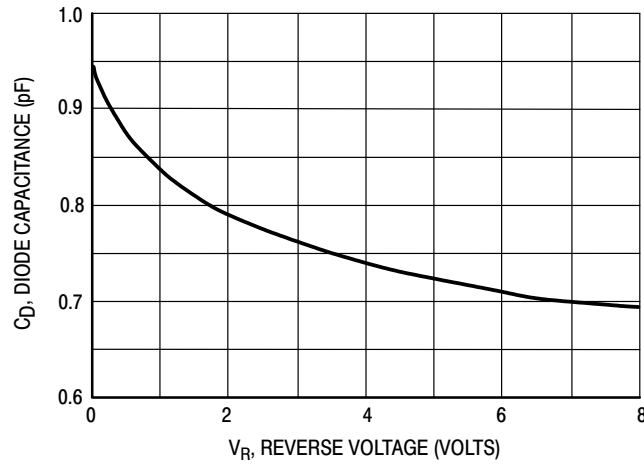
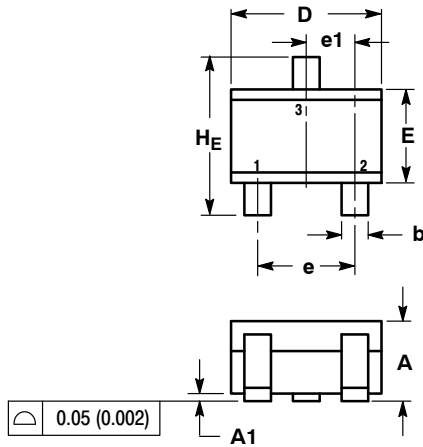


Figure 5. Capacitance

# BAV70WT1G, SBAV70WT1G

## PACKAGE DIMENSIONS

SC-70 (SOT-323)  
CASE 419-04  
ISSUE N

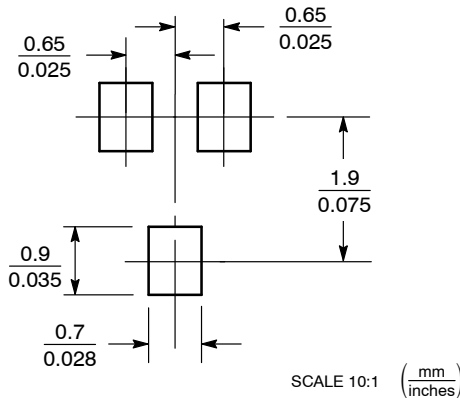


NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095

STYLE 5:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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